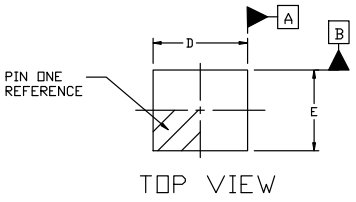
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

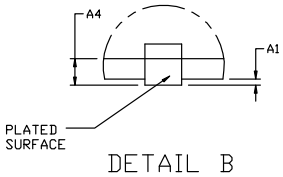


WDFNW6 1.4x1.2, 0.5P (DUAL)
CASE 515AT
ISSUE O

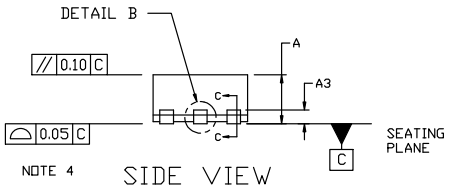
DATE 04 OCT 2022



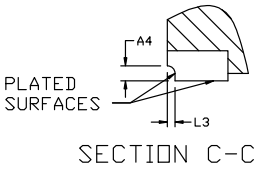
TOP VIEW



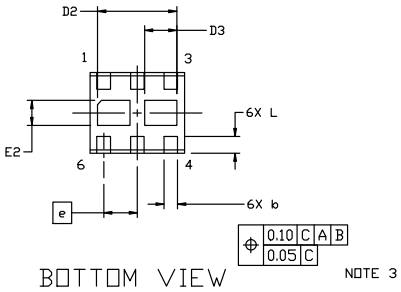
DETAIL B



SIDE VIEW



SECTION C-C

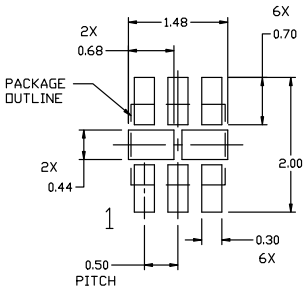


BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO THE PLATED TERMINALS AND IS MEASURED BETWEEN 0.10 AND 0.20mm FROM THE TERMINAL TIP.
4. PROFILE APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

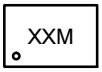
	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	0.65	0.75	0.80
A1	0.00	-----	0.05
A3		0.20 REF	
A4	0.10	-----	-----
b	0.15	0.20	0.25
D	1.30	1.40	1.50
D2	1.13	1.18	1.23
D3	0.43	0.48	0.53
E	1.10	1.20	1.30
E2	0.32	0.37	0.42
e		0.50 BSC	
L	0.15	0.25	0.35
L3	0.00	0.05	0.10



RECOMMENDED
MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XX = Specific Device Code
M = Month Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98AON27356H**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**WDFNW6 1.4x1.2, 0.5P (DUAL)**	**PAGE 1 OF 1**

onsemi and onsemi are trademarks of Semiconductor Components Industries, LLC dba **onsemi** or its subsidiaries in the United States and/or other countries. **onsemi** reserves the right to make changes without further notice to any products herein. **onsemi** makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does **onsemi** assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. **onsemi** does not convey any license under its patent rights nor the rights of others.

© Semiconductor Components Industries, LLC, 2022